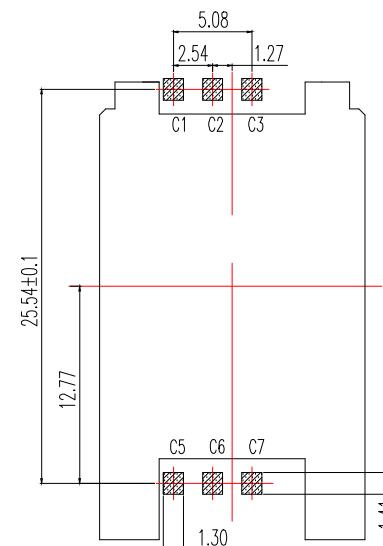
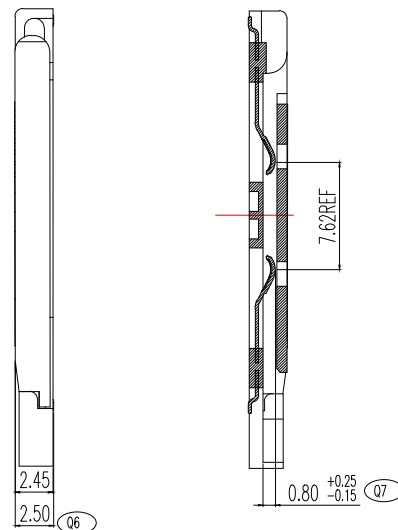
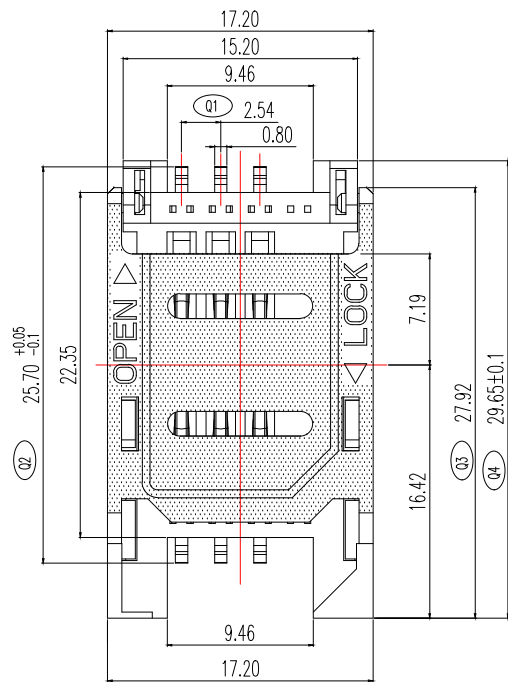
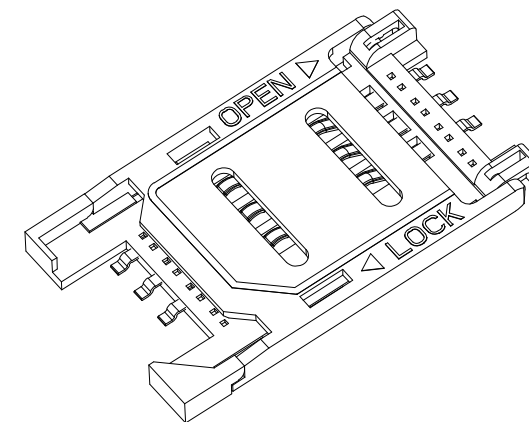
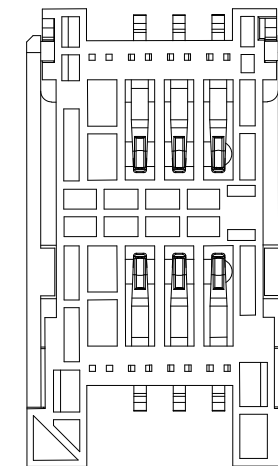




PAD AREA
KEEP OUT AREA
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05



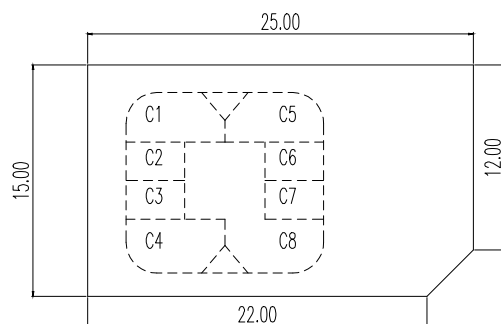
Q8 SPECIFICATION:

- 1.寿命:10000CYCLES MIN.
- 2.CONTACT FORCE:0.2~1.0N.(卡片厚度0.76MM)
- 3.接触阻抗:50m Ω , TYPICAL,100m Ω MAX.
- 4.绝缘阻抗:MIN 1000M Ω /500V DC .
- 5.OPEN/LOCK FORCE: 6N $\pm$ 3N
- 6.平贴:IR前后CP8 0.10MM MAX;塑胶0.20MM MAX.
- 7.(QX)为重点检验尺寸.
- 8.工作范围:-40 $^{\circ}$ ~+ 85 $^{\circ}$

MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

Table A

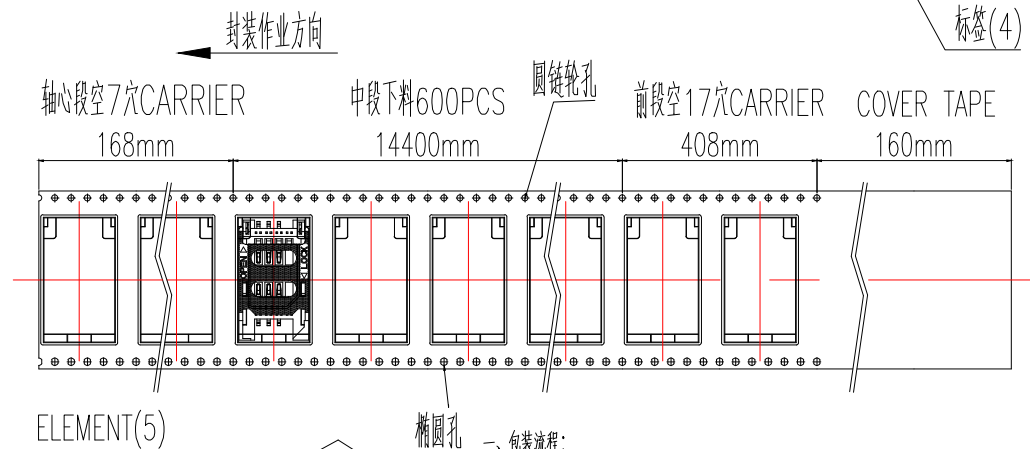
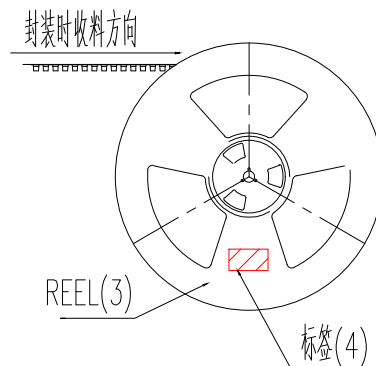
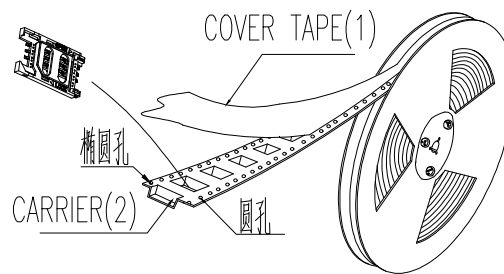
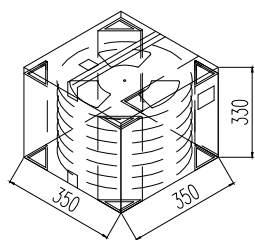
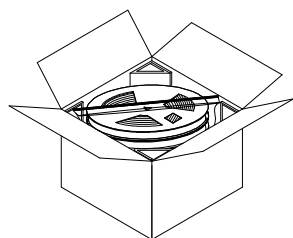
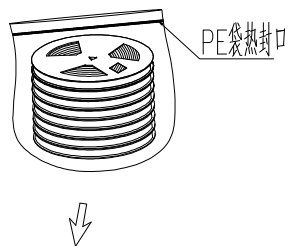
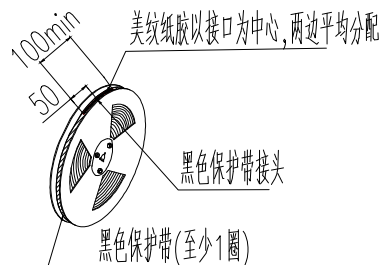
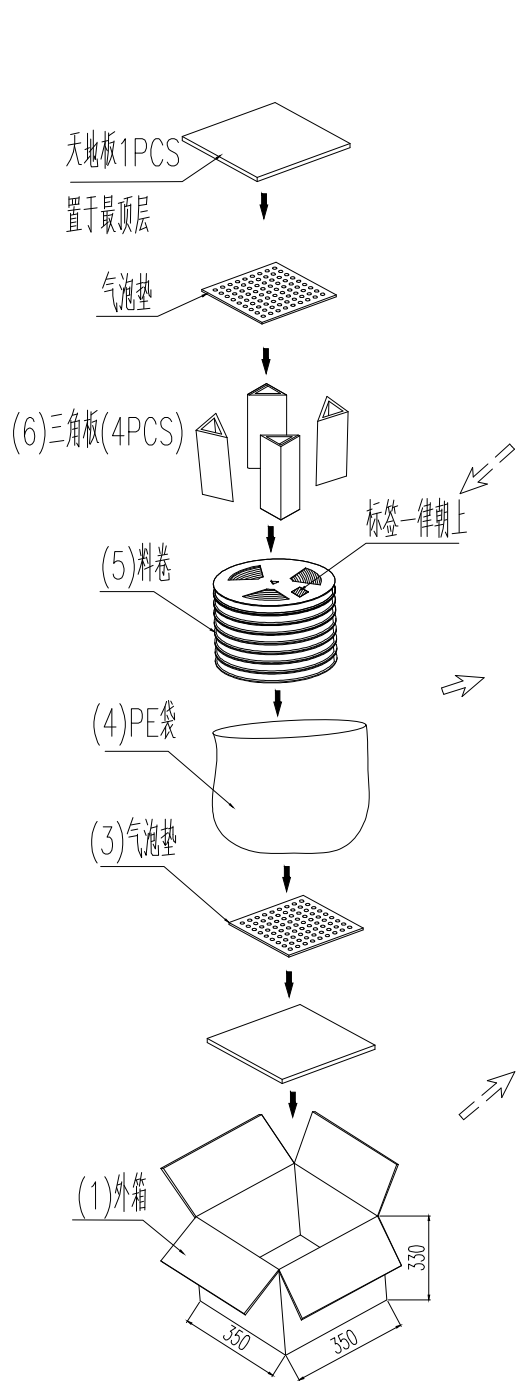
材质	塑胶	LCP E130i BK HF
	端子	C5210R-H T=0.20mm HF
端子电镀	整体打镍底50U"MIN,接触区刷金3U"MIN,焊接区浸镀纯锡100U"MIN.	



制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		审核 CHECK	批准 APPROVAL	单位 UNITS	比例 SCALE	1:1	料号 PART NO.	品名 TITLE	客户料号 CUTM.NO.	版本 REV.	页次 SHEET	A
			X $\pm$ 0.15	X' $\pm$ 3"											
			.X $\pm$ 0.10	.X' $\pm$ 2"											
			.XX $\pm$ 0.08	.XX' $\pm$ 1"											

EMMA
EVA
JADE

Bossie (博锡)



一、包装流程:

1. 成品置于Carrier Tape中,金属零件以不接触Carrier Tape为原则。
2. 以冷封式Cover Tape与REEL紧密封好,每盘REEL共装600Pcs成品;
3. 每盘包装好后需在REEL带外围黑色保护带绕1圈包好,并以至少100mm的美纹纸胶;
4. 将成品之Label贴于REEL椭圆定位孔另一侧之卷盘上;
5. 先置入一瓦楞纸板于纸箱底部,再置一张气泡布于瓦楞纸上,后将Reel平置于一防水袋,标签统一朝上装放(一箱共装6个Reel),封好口后置于箱中;
6. 将三角板置于箱中四个角落,再置入一张气泡布于Reel之上,后置一块瓦楞纸板于最顶层;
7. 以Tape封合,并贴上成品包装标签。

二、包装要求:

1. 成品包装前后均需空穴,具体要求如图示;
2. 三角板置入箱中须高于REEL重叠总高度,但需低于纸箱顶面15mm以上,以确保封口后不会有外拱现象;
3. REEL盘不可有晃动现象。

三、尾数箱包装流程及要求同上。

制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA	料号 PART NO.	BX-SIM-2.5HJ	版本 REV.	A
			X $\pm$ 0.15	X' $\pm$ 3"						
			.X $\pm$ 0.10	.X' $\pm$ 2"	审核 CHECK	EVA	品名 TITLE	MINI SIM CARD HINGED 2.5HJ 6P 封装	页次 SHEET	1/1
			.XX $\pm$ 0.08	.XX' $\pm$ 1"	核准 APPROVAL	JADE	客户料号 CUTM.NO.			
					单位 UNITS	MM	比例 SCALE	1:1		

Bossie (博锡)